

To our customers,

Old Company Name in Catalogs and Other Documents

On April 1st, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: <http://www.renesas.com>

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

Send any inquiries to <http://www.renesas.com/inquiry>.

RENESAS TECHNICAL UPDATE

Classification of Production	Packages		No	TN-PKG-096A/E	Rev	1
THEME	Information of Pb-Free (High Temp.) reflow application	Classification of Information	① Spec change 2. Supplement of Documents 3. Limitation of Use 4. Change of Mask 5. Change of Production Line			
PRODUCT NAME	standard logic products of SOP (JEDEC) 8 pin HD151TS300 Series	Lot No.	Reference Documents	—	term of validity	
		4A1			From Jan / 2004	

1. Change contents

(1) Lead plating specification change

	Current	New
Plating material	Sn-Pb	Ni/Pd/Au

The plating of the terminal will be changed to Ni/Pd/Au.
Pd : Palladium

(2) Label specification change

Print it in the Label with [Pb-Free T.]
(It means that it does not use lead (Pb) for terminals)

The diagram shows a rectangular label with the following text and barcodes:

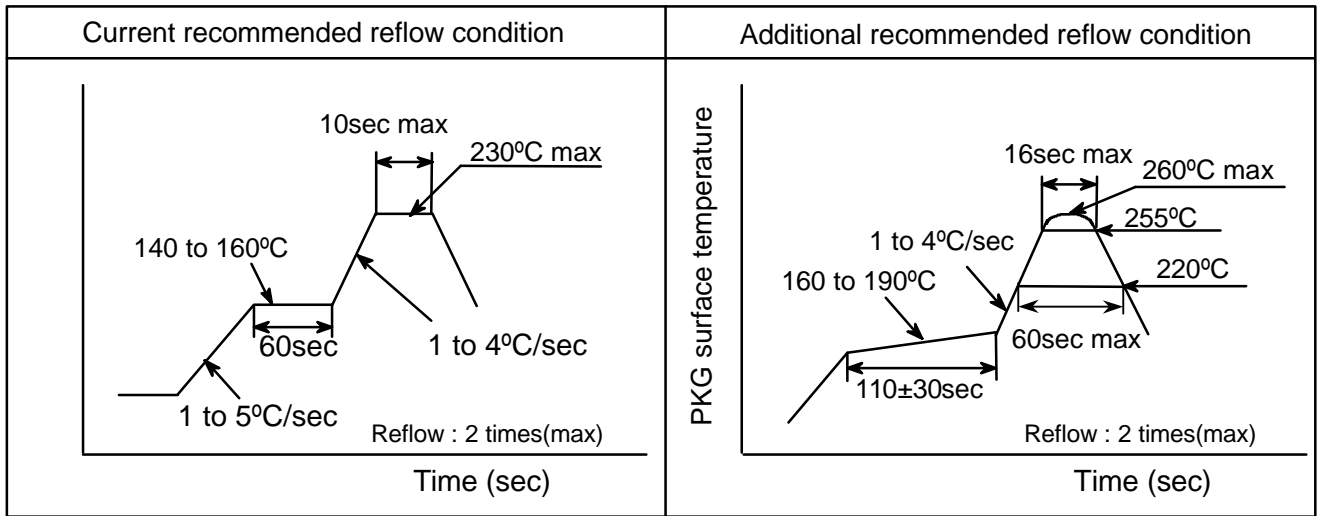
- Top line: P 4A1 2500 UJ13219-02 **RENESAS**
- Barcode 1
- Line 2: P/N HD151TS302RPEL Pb-Free T.
- Barcode 2
- Line 3: D/N 151TS302RPEL-E
- Barcode 3
- Line 4: T/C 4A1 UJ13219-02 QTY 2500 ****
- Barcode 4
- Line 5: 04/01/01
- Line 6: MADE IN MALAYSIA

Annotations with arrows:

- Product Name** points to the top line of text.
- Device Name** points to the P/N line.

Example label (Tape Reel & Reel Inner Box)

(3) Addition of high temperature reflow condition



2. Reason of changes
Environmental pollution prevention.

3. Applied timing
3.1 This change is scheduled to apply from Jan. 2004.
3.2 There is no change regarding the electric characteristics and reliability.

4. Others
4.1 The samples for evaluation have been prepared.
4.2 Lead-free compatible soldering conditions for DIP.
(1) Solder-Dipping
Maximum temperature : 260°C for 10 sec. one time
(2) Soldering iron
Maximum lead temperature : 260°C for 3 sec. However, the temperature of the soldering iron itself should not exceed 350°C.